



FE-401U

Product Description

Shin-Etsu FE-401 U is a fluorosilicone/silicone blend. It is designed to process well in molding applications.

Product Features

- Good fuel and oil resistance.
- Usable over a broad temperature range.

Typical Applications

- Chemical resistant packings and seals.
- Oil and fuel resistant seals, O rings, diaphragms for automotive.
- Heat and cold resistant packings, connectors, gaskets for aeronautical applications.

Packaging Information

- 44lb or 88lb Box
- 50lb Box

Typical Properties

Type of HCR	Fluorosilicone
Cure Agent	DCP-40
Durometer	48
Tensile Strength (psi)	1600
Elongation (%)	540
Specific Gravity	1.31
Tear Die B (ppi)	200
Compression Set (%)	20
Comp. Set Time (hours)	22
Comp. Set Temp. (°C)	205
Comp. Set Temp. (°F)	401
Press Cure/Post Cure	Post
Post Cure Time (hours)	4
Post Cure Temp. (°C)	220
Post Cure Temp. (°F)	428

Note: Values are not for specification purposes.

Warranty- The information and data contained herein are believed to be accurate and reliable; however it is the user's responsibility to determine suitability of use. Since Shin-Etsu Silicones, Inc. cannot know all of the uses to which its products may be put or the conditions of use, it makes no warranties concerning the fitness or suitability of its products for a particular use or purpose. You should thoroughly test any proposed use of our products and independently conclude satisfactory performance in your application. Likewise, if the manner in which our products are used requires governmental approval or clearance, you must obtain it. Shin-Etsu Silicones, Inc. warrants only that its products will meet its specifications. There is no warranty of merchantability of fitness of use, nor any other expressed or implied warranties. The user's exclusive remedy and Shin-Etsu Silicones, Inc.'s sole liability is limited to refund of the price or replacement of any product shown to be otherwise than as warranted. Shin-Etsu Silicones, Inc. will not be liable for incidental or consequential damages of any kind. Suggestions of uses should not be taken as inducements to infringe any patents.